



## Material Content Data Sheet



<b>Sales Product Name</b>		BSL211SP H6327		<b>Issued</b>		24. January 2018		
<b>MA#</b>		MA001626256						
<b>Package</b>		PG-TSOP6-6-6		<b>Weight*</b>		13.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.07		690	
	noble metal	gold	7440-57-5	0.036	0.27		2675	
	inorganic material	silicon	7440-21-3	0.412	3.03	3.37	30313	33678
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		435	
	non noble metal	chromium	7440-47-3	0.018	0.13		1304	
	non noble metal	copper	7440-50-8	5.882	43.28	43.46	432846	434672
wire	non noble metal	copper	7440-50-8	0.039	0.29	0.29	2889	2889
encapsulation	organic material	carbon black	1333-86-4	0.067	0.49		4938	
	plastics	epoxy resin	-	1.443	10.62		106165	
	inorganic material	silicondioxide	60676-86-0	5.201	38.27	49.38	382689	493792
leadfinish	non noble metal	tin	7440-31-5	0.299	2.20	2.20	21996	21996
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12973	12973
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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